PREFACE

Dear Distinguished Delegates and Guests,

International Conference on Sport, Arts Materials and Management Science (SAMMS) 2012 will be held on May 4-6, 2012, in Chongqing, China, serving as a platform for expertise exchange. SAMMS2012 had drawn the attention of researchers from various disciplines: Sport Materials and Applications, Advanced medicine materials and Applications, Arts materials and its influence on education, Building materials and applications, Vibration and Control, Modeling, Simulation, Control and Applications, etc.

Persons who attended the conference were engineers, scientists, managers of various companies and professors of the universities abroad and home. We have had record number of submission 423 this year. Only original and unpublished paper would be considered, and 58 papers have been accepted for presentation at the conference and will be published by TTP, in Advanced Materials Research (AMR) Journal (ISSN: 1022-6680), which is online available in full text via the platform www.scientific.net. AMR should be indexed by EI according the previous TTP index results.

We express our special gratitude to all the members of the General Committee Chairs, Program Committee Chairs, Technical Program Committee and Steering Committee who worked so hard to prepare the conference and who supported the conference so professionally.

Our deep thanks also go to the sponsors: Shanghai Jiao Tong University, University of Science and Technology Beijing, Chongqing Normal University, Chongqing University of Arts and Sciences, Hunan Institute of Engineering, Zhejiang Gongshang University, their kind support in making SAMMS 2012 possible.

Finally, we would like to thanks all the authors, speakers and participants of this conference for taking part in and contributing to the International Conference on Sport, Arts Materials and Management Science (SAMMS) 2012.

We hope you have a unique, rewarding and enjoyable week at SAMMS 2012 in Chongqing.

With our warmest regards,

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May 4-6, 2012
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